

Compal Confidential

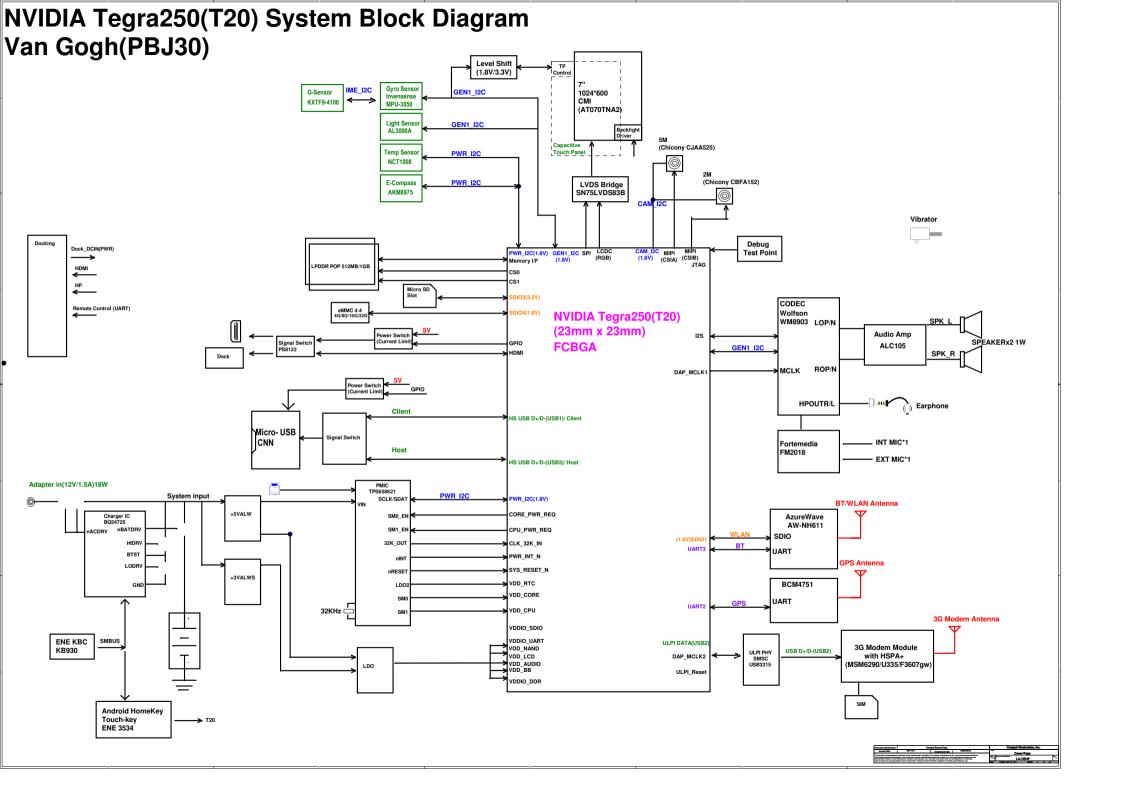
PBJ30 Schematics Document

Nvdia(T20) + DDRII

2011-04-12

REV: 1.0 (PVT)

Security Classification	Cor	npal Secret Data			Compal Electronics, Inc.
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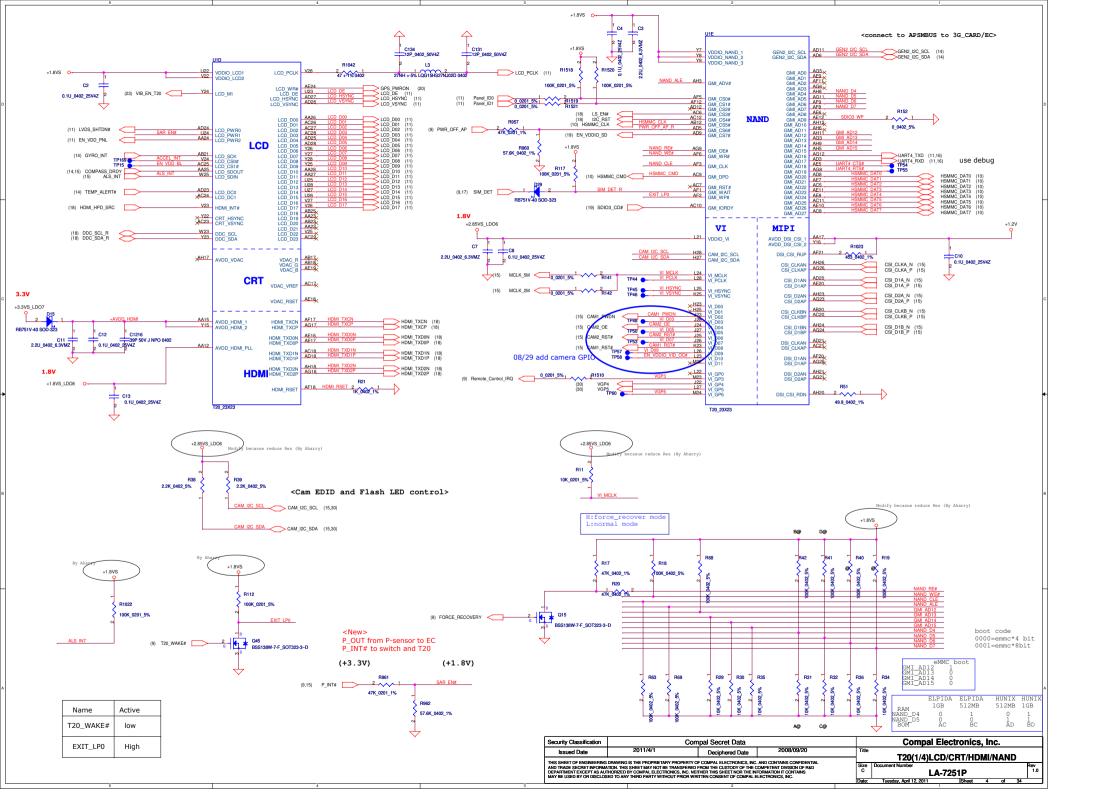


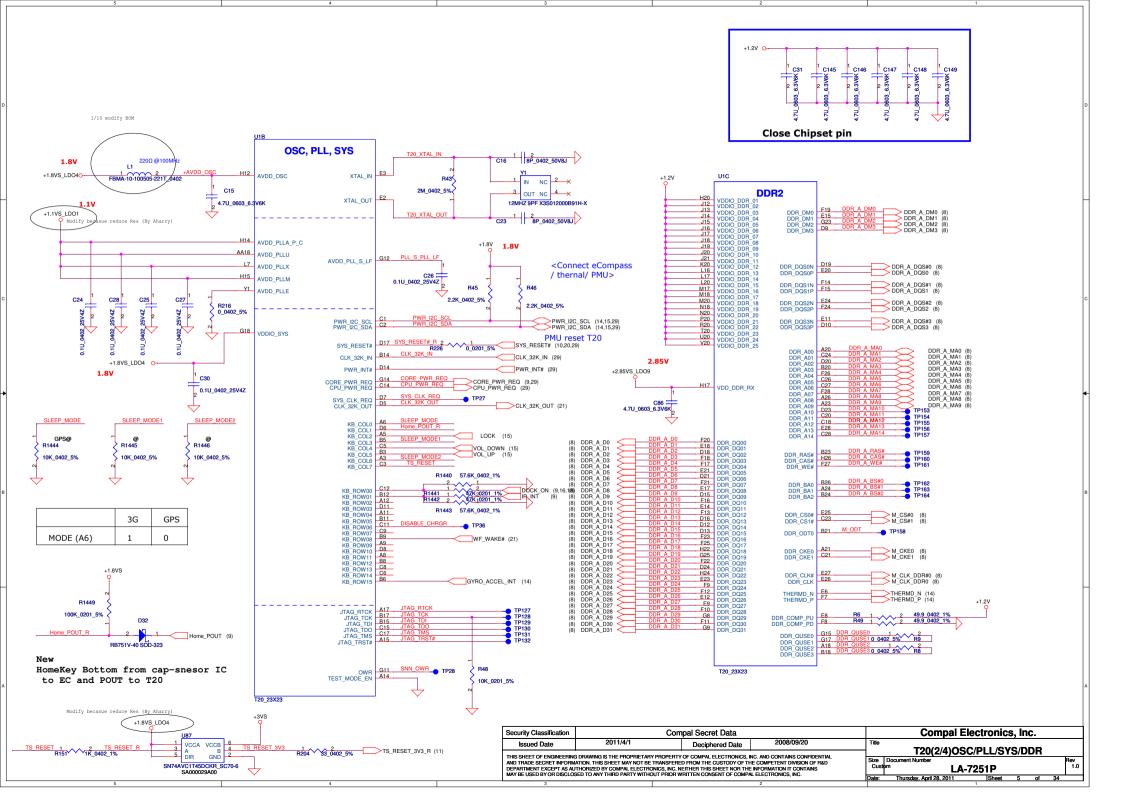
Voltage Rails

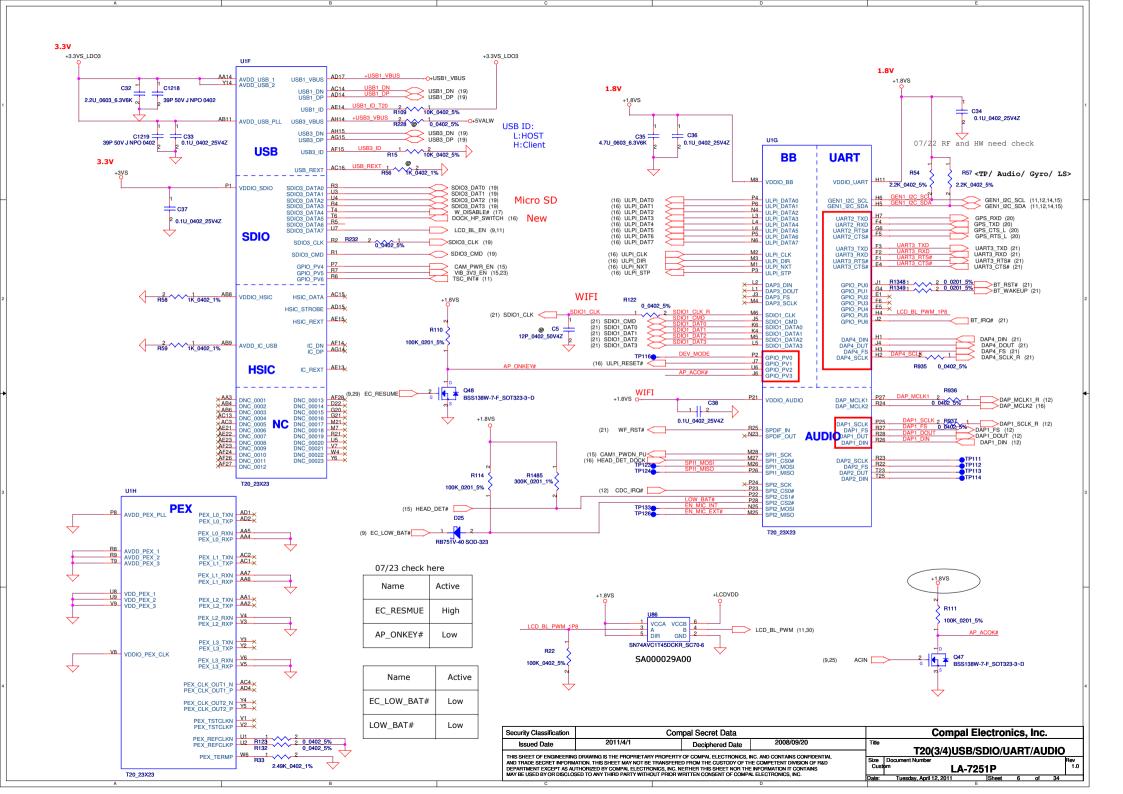
Power Plane	Description
VIN	Adapter power supply (19V)
B+	AC or battery power rail for power circuit.
+1.2VS_SM0	Core voltage for CPU
+1.0VS_SM1	CPU voltage for CPU
+1.1VS_LDO1	AVDD_PLL power rail
+1.2VS_LDO2	T20 RTC power rail
+1.8VS_LDO4	T20 system power rail
+3.3VS_LDO3	T20 USB power rail
+2.85VS_LDO5	Core voltage for EMMC
+2.85VS_LDO6	Core voltage for CAMERA
+3.3VS_LDO7	T20 HDMI power rail
+1.8VS_LDO8	T20 HDMI PLL power rail
+2.85VS_LDO9	T20 DDR RX power rail
+3VALW	3.3V always on power rail
+3VS	3.3V switched power rail for standby mode
+5VALW	5V always on power rail
+1.8VS	1.8V always on power rail
+1.8VS_S3	1.8V switched power rail for standby mode
+3.3VS_RTC	RTC power

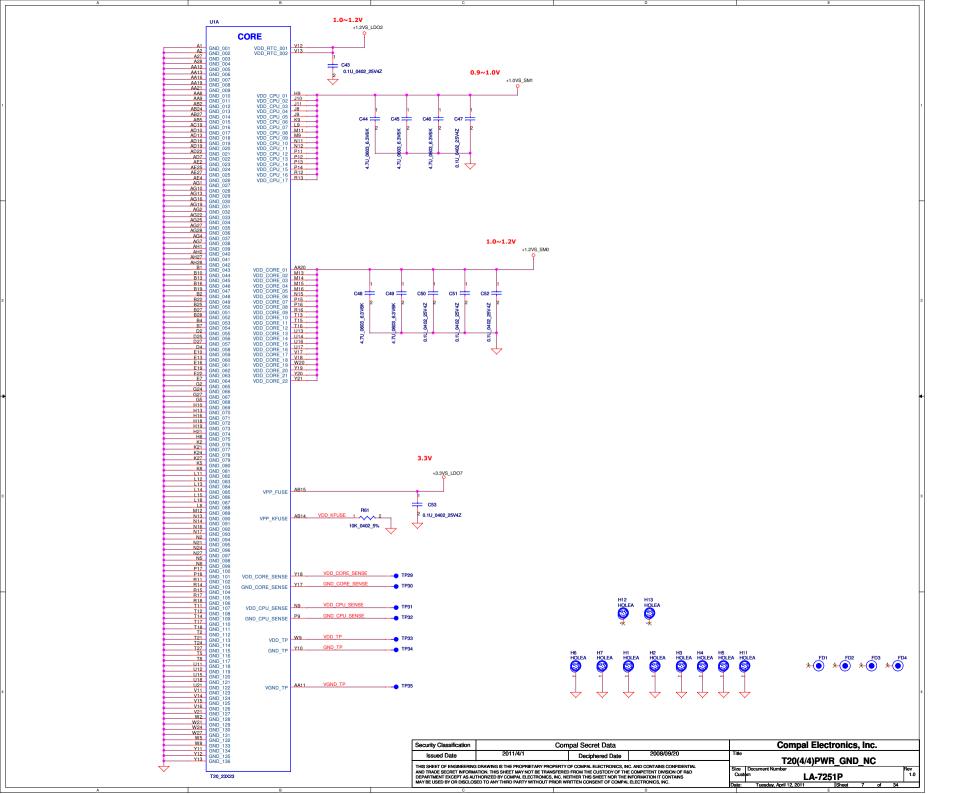
PWR_I2C addres	S	CAM_I2C a	address
Device	Address	Device	Address
PMU	0110 100x b	Camera 5M	0111 101x b
e-Compass	0001 100x b	Camera 2M	0111 100x b
Temperature sensor	1001 100x b	LED Flash	0110 011x b
GEN1_I2C		TS_I2C	
Device	Address	Device	Address
Audio Codec	0011 010x b		
Light sensor	0011 100x b		
Gyro	1101 000x b		
G-sensor	0001 111x b		
Touch-Pad	1100 111x b		
GEN2_I2C		AP_SMB	
Device	Address		
EC	1011 000x b	Device	Address
EO OMB			
EC_SMB		IME I2C	
Device	Address	 Device	Address
Echo Cancellation	1100 000x b		
DDC I2C		HDMI_DI	DC 12C
			00_120

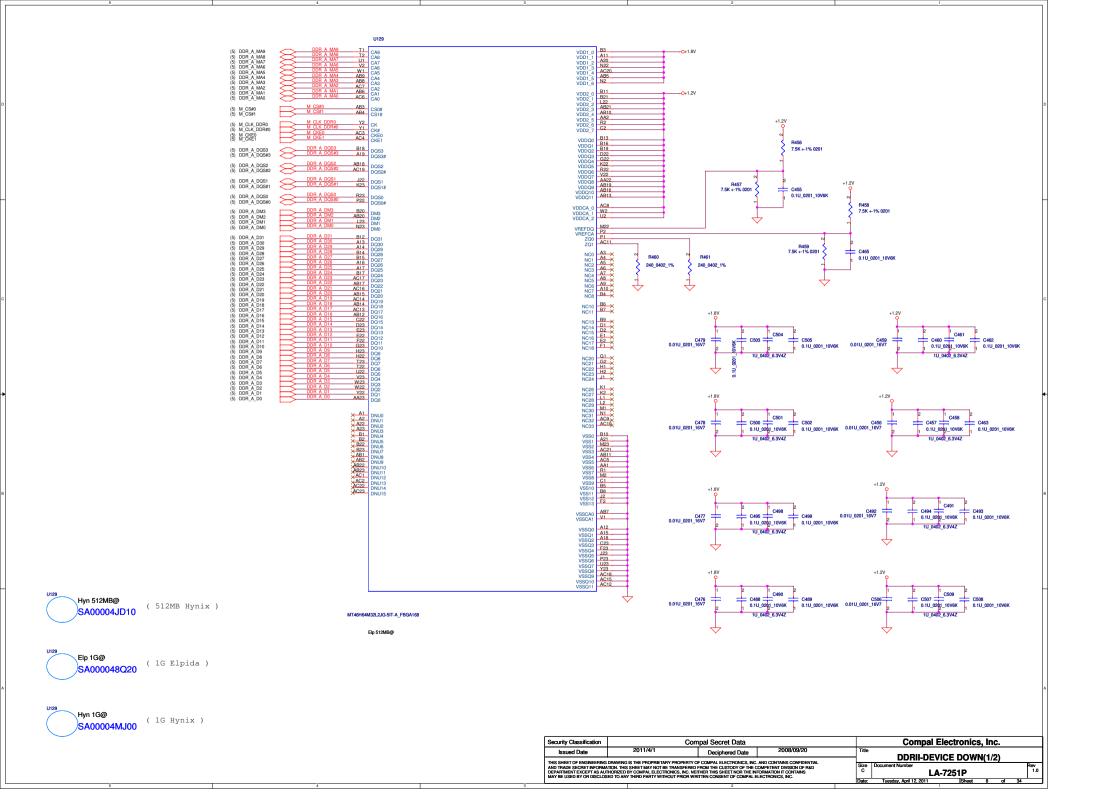
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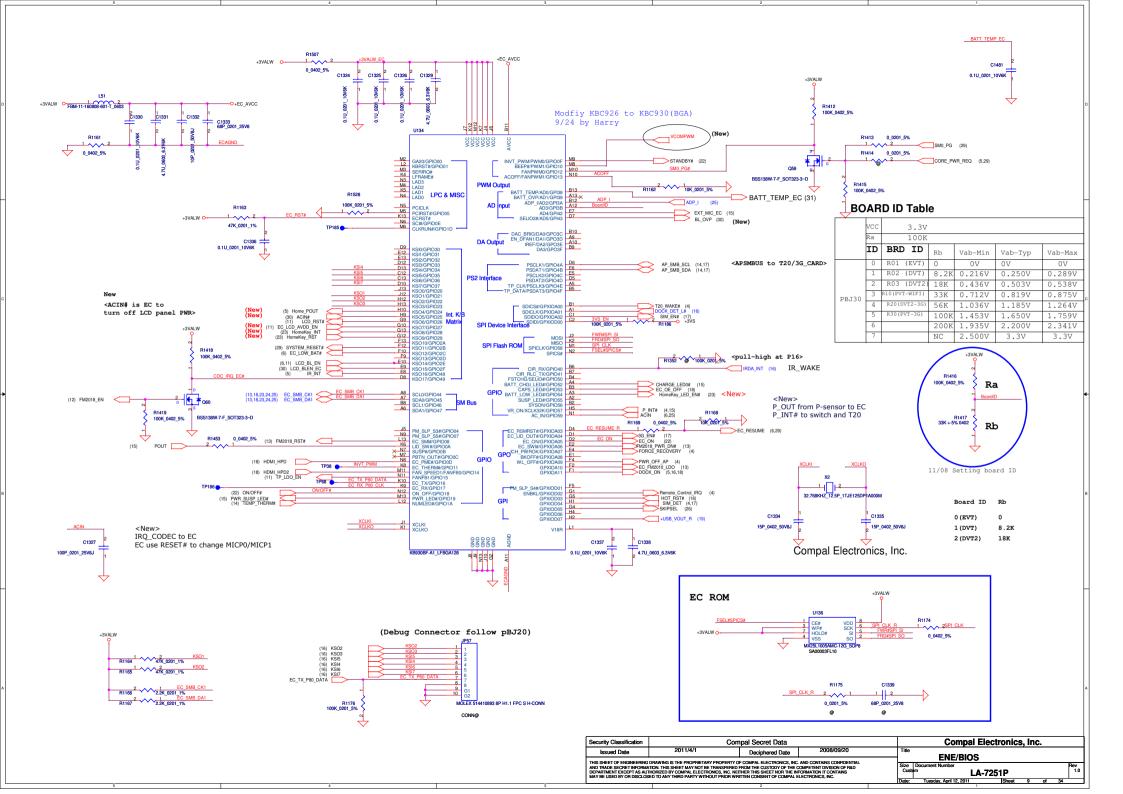


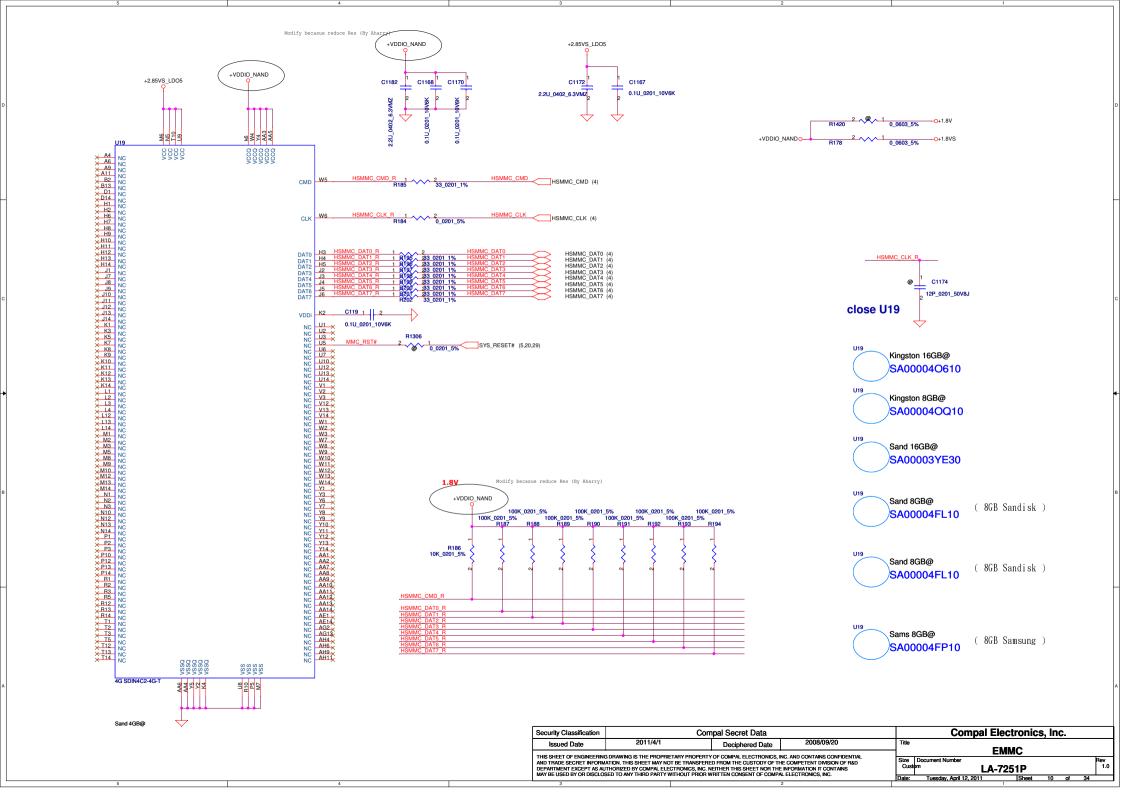


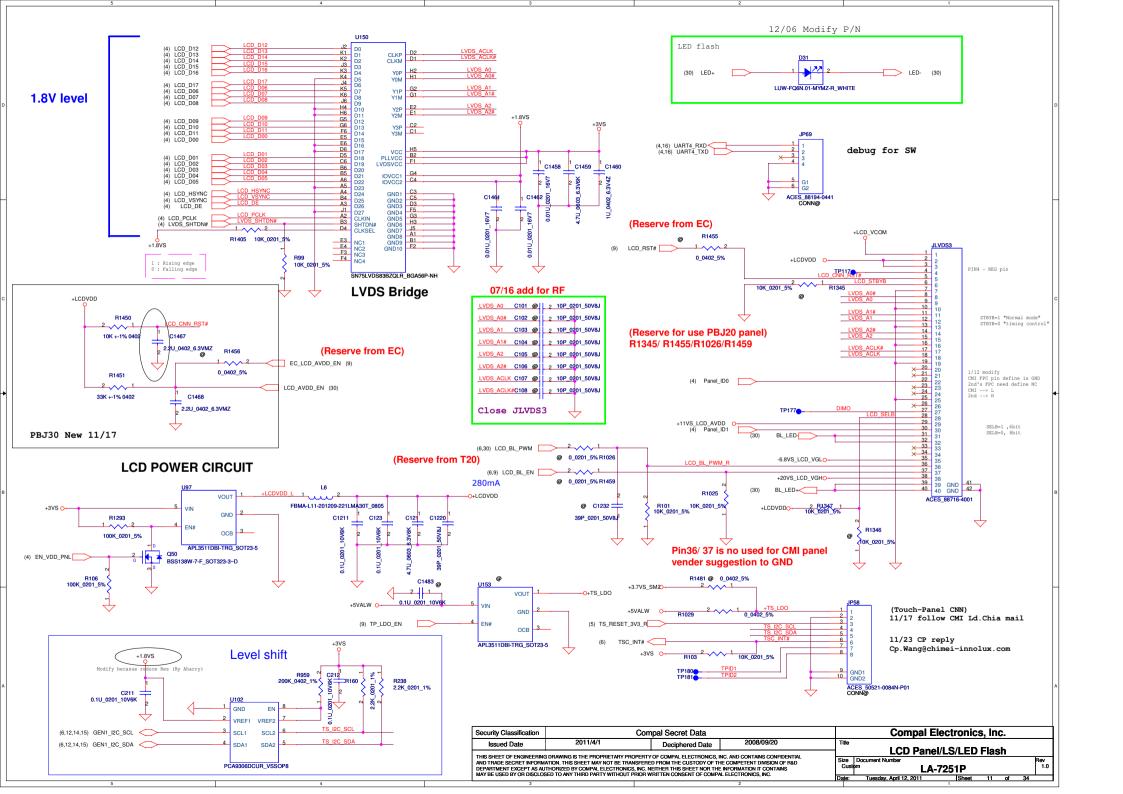


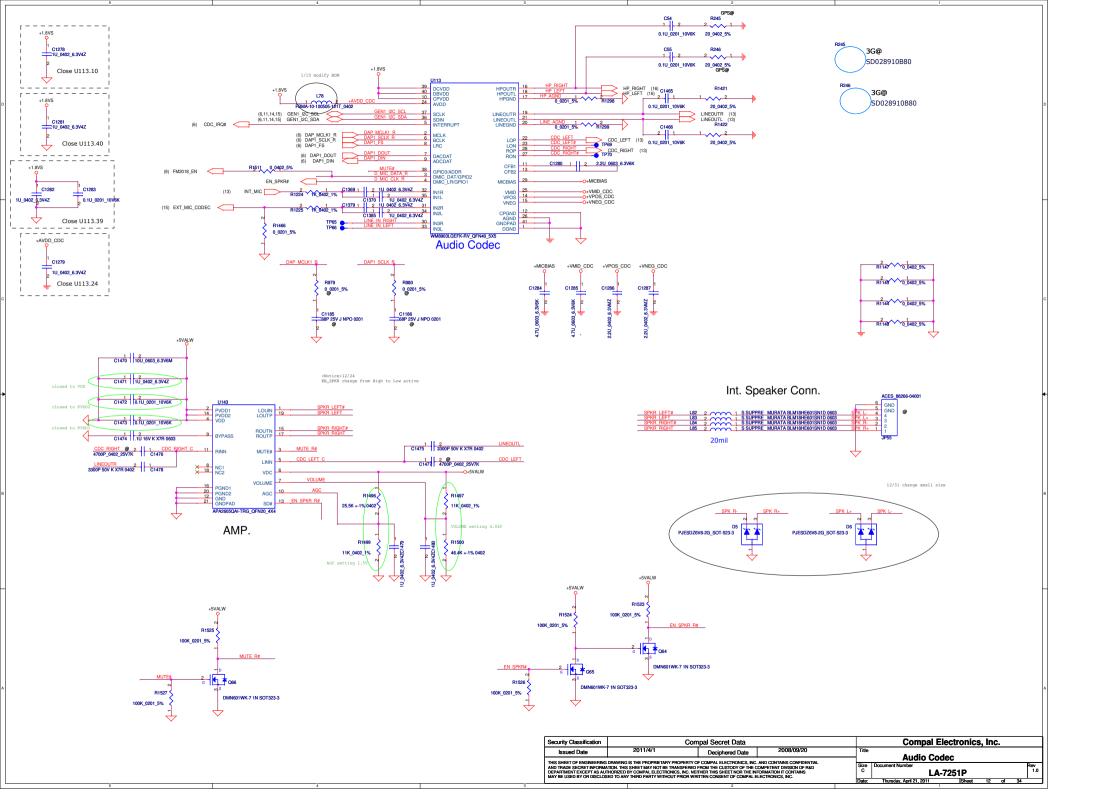


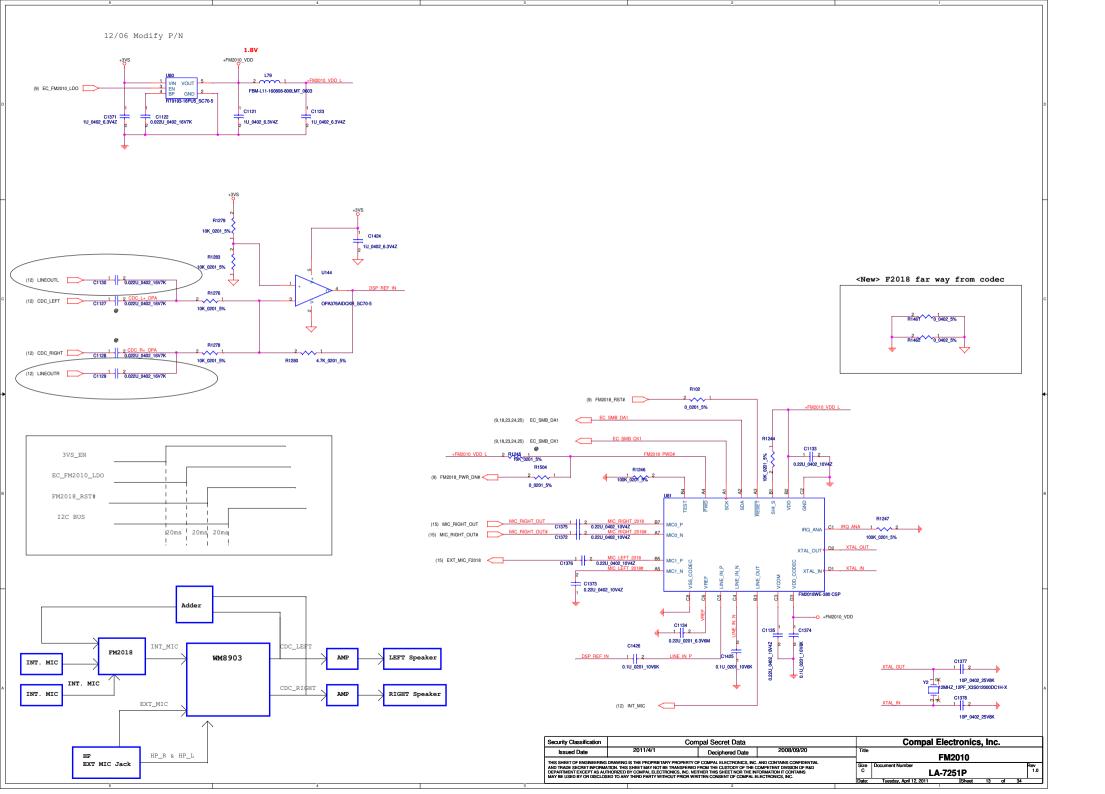


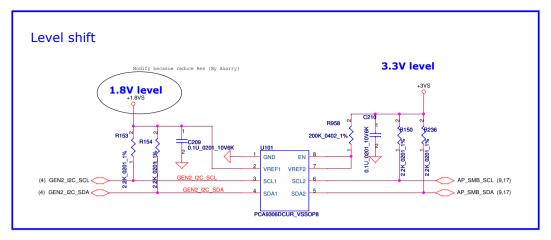




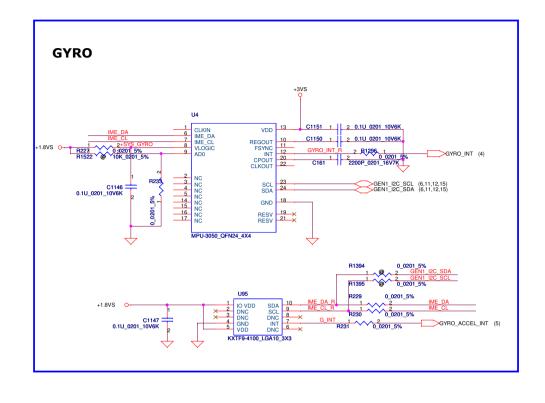


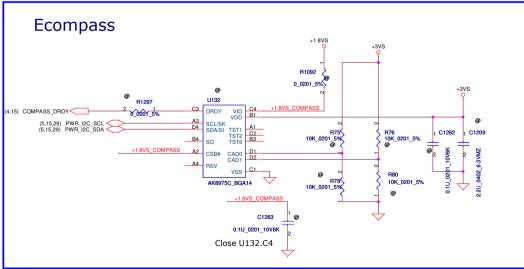


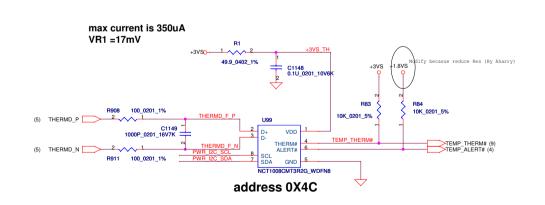




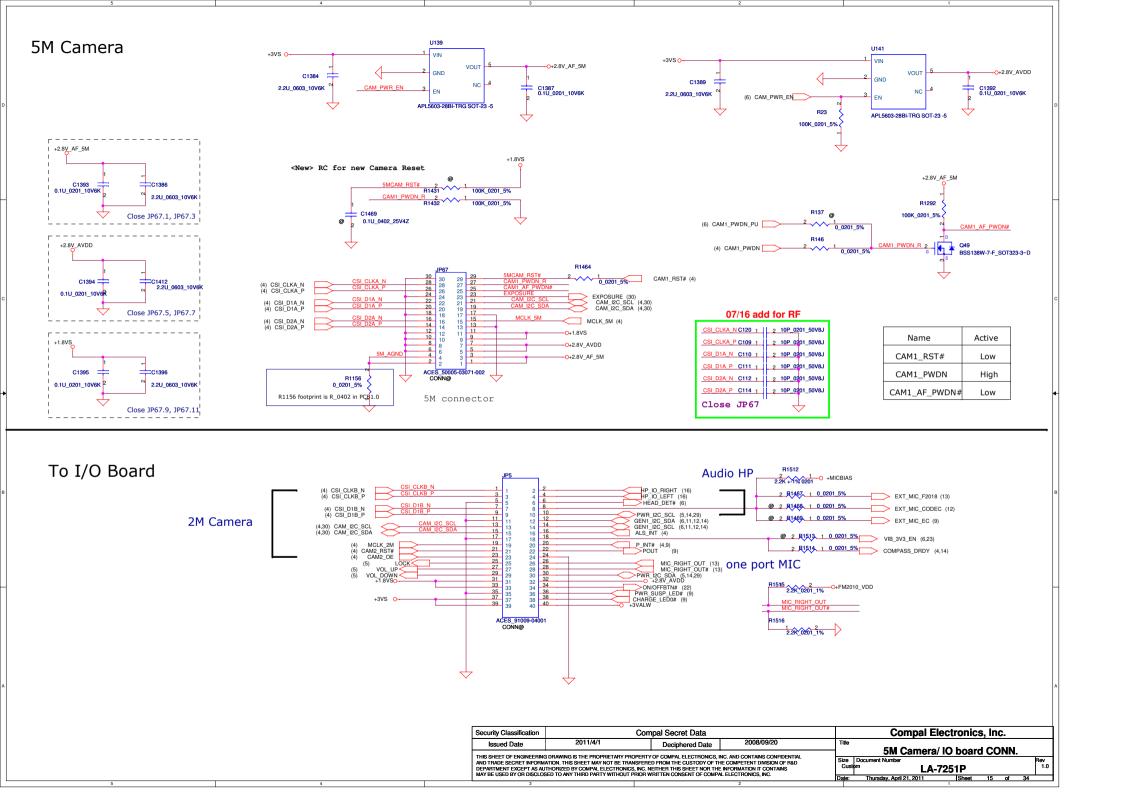
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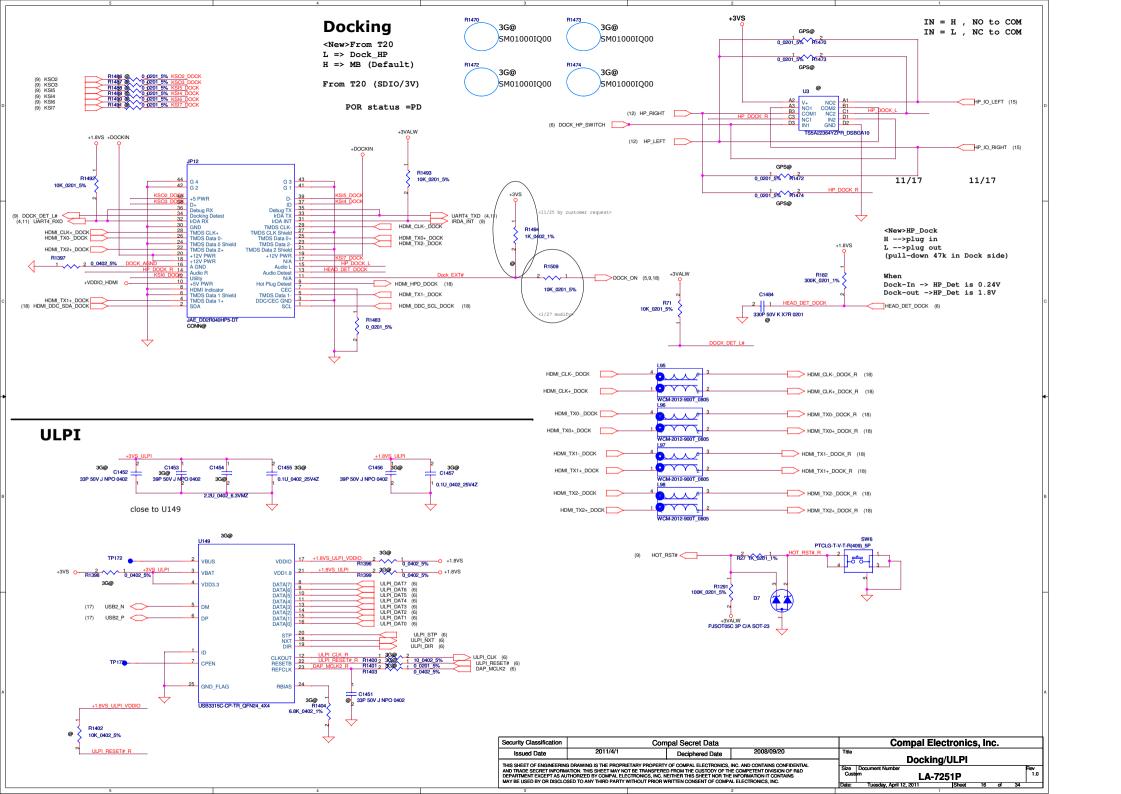


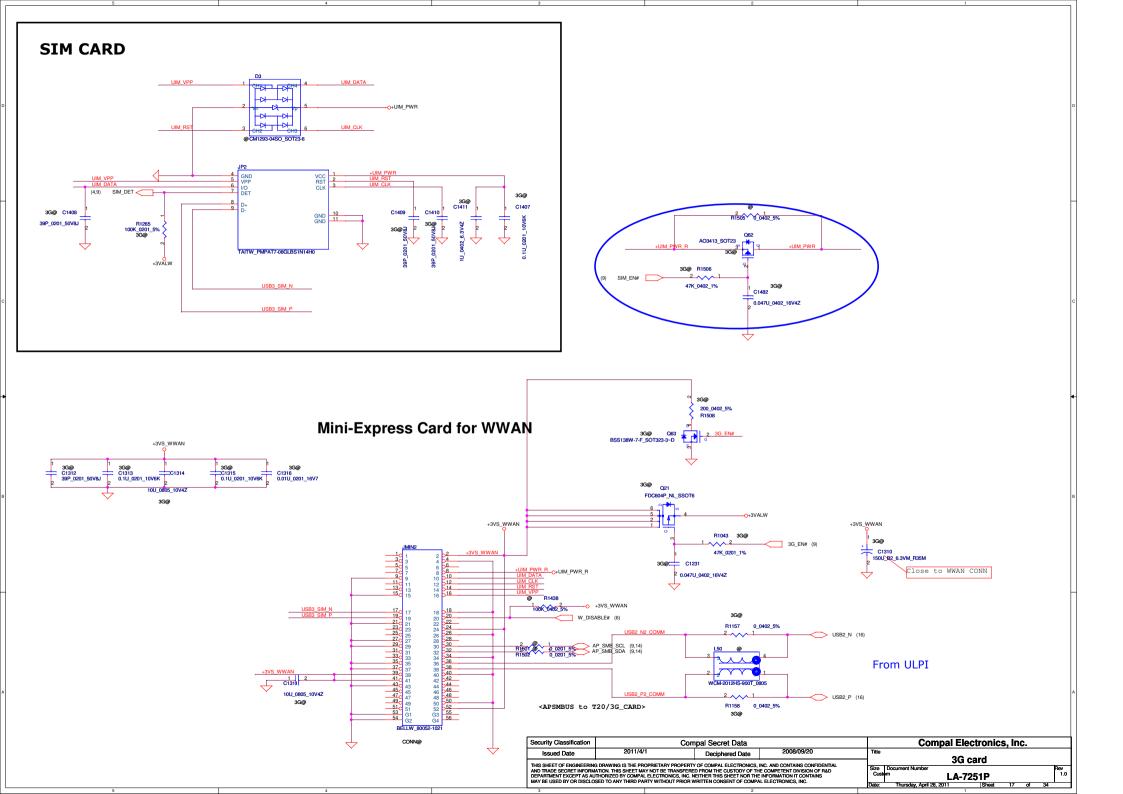


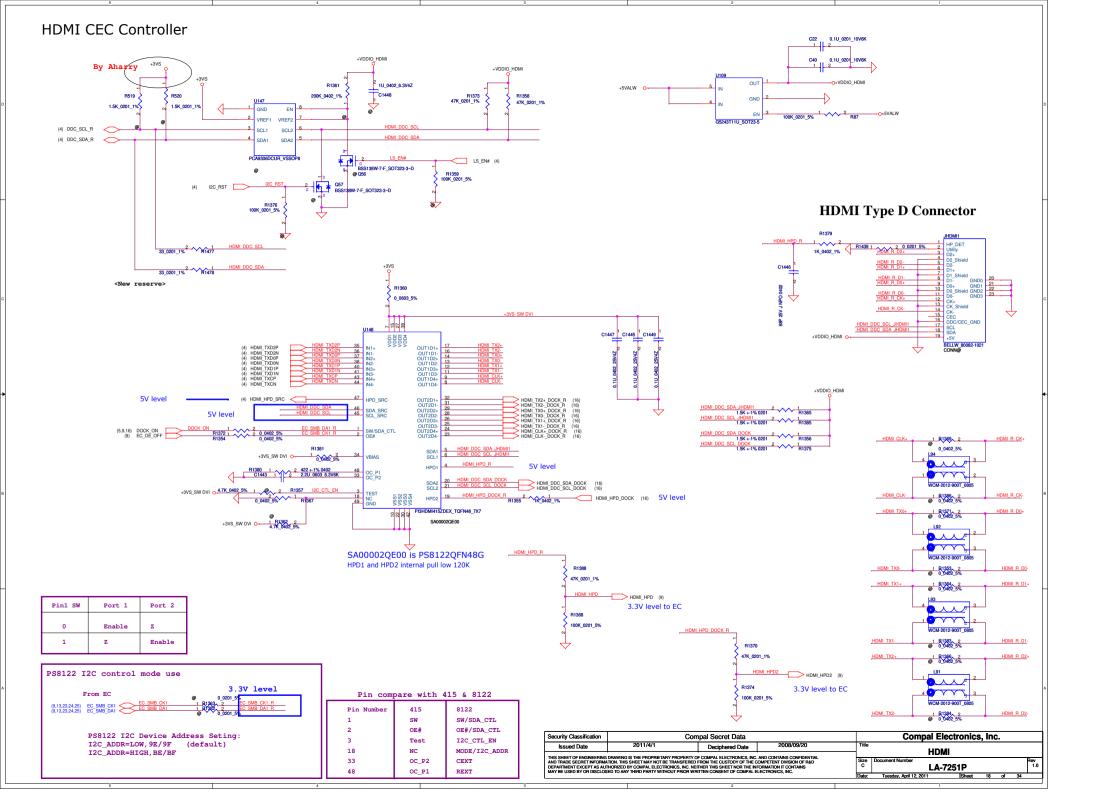


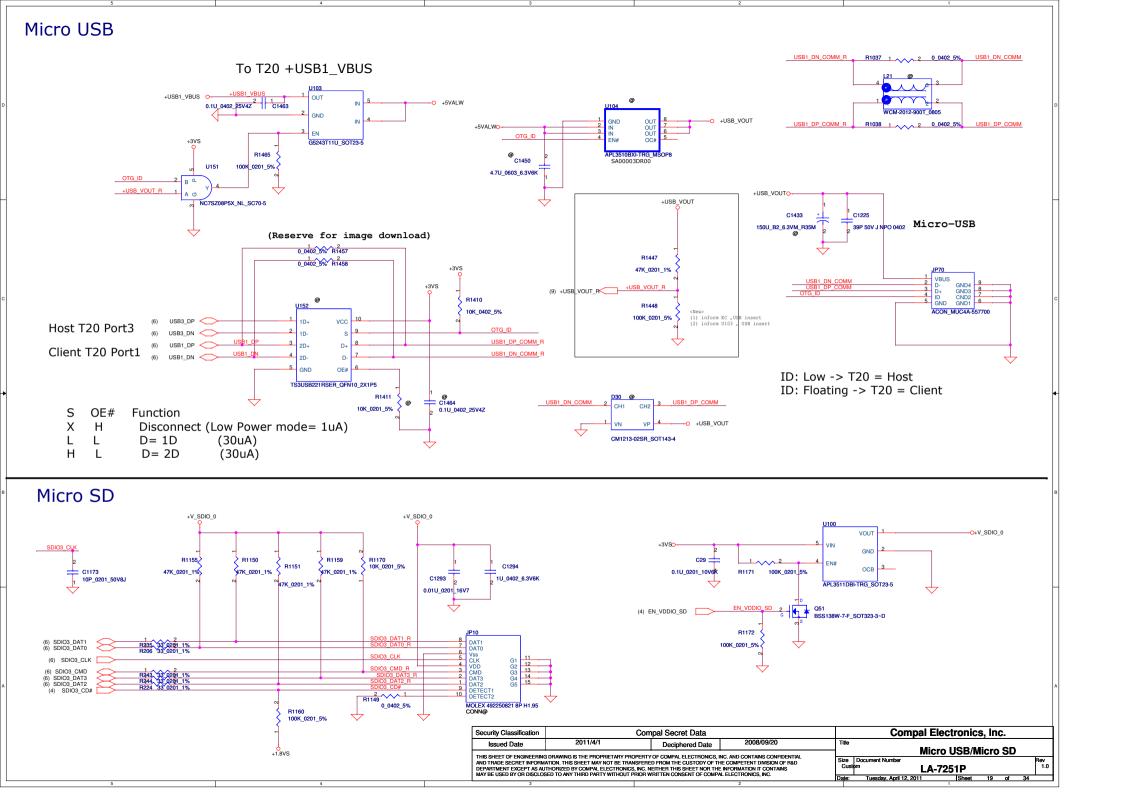
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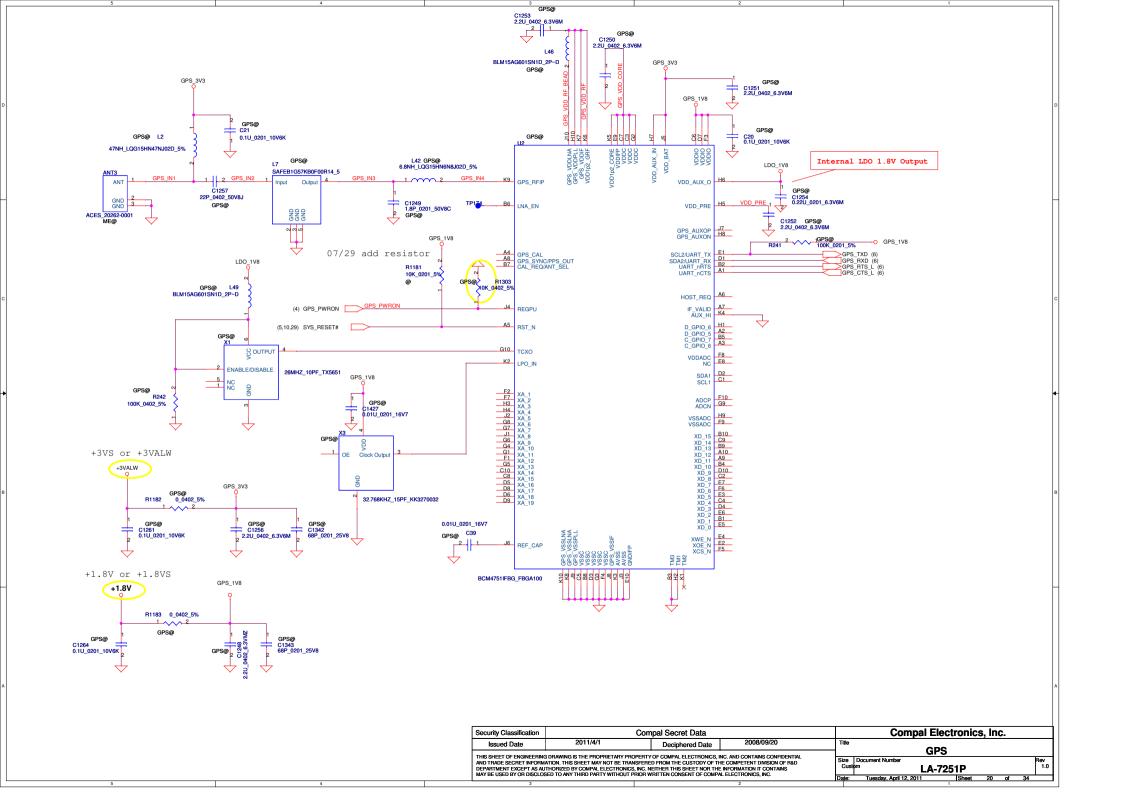


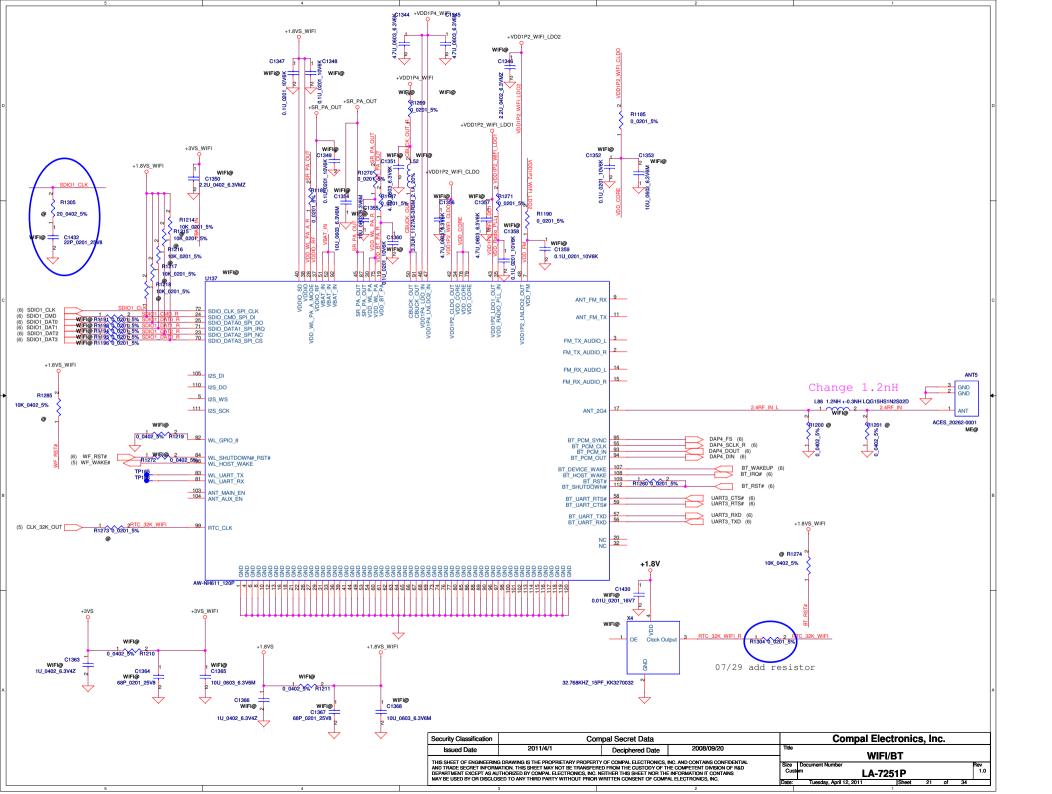


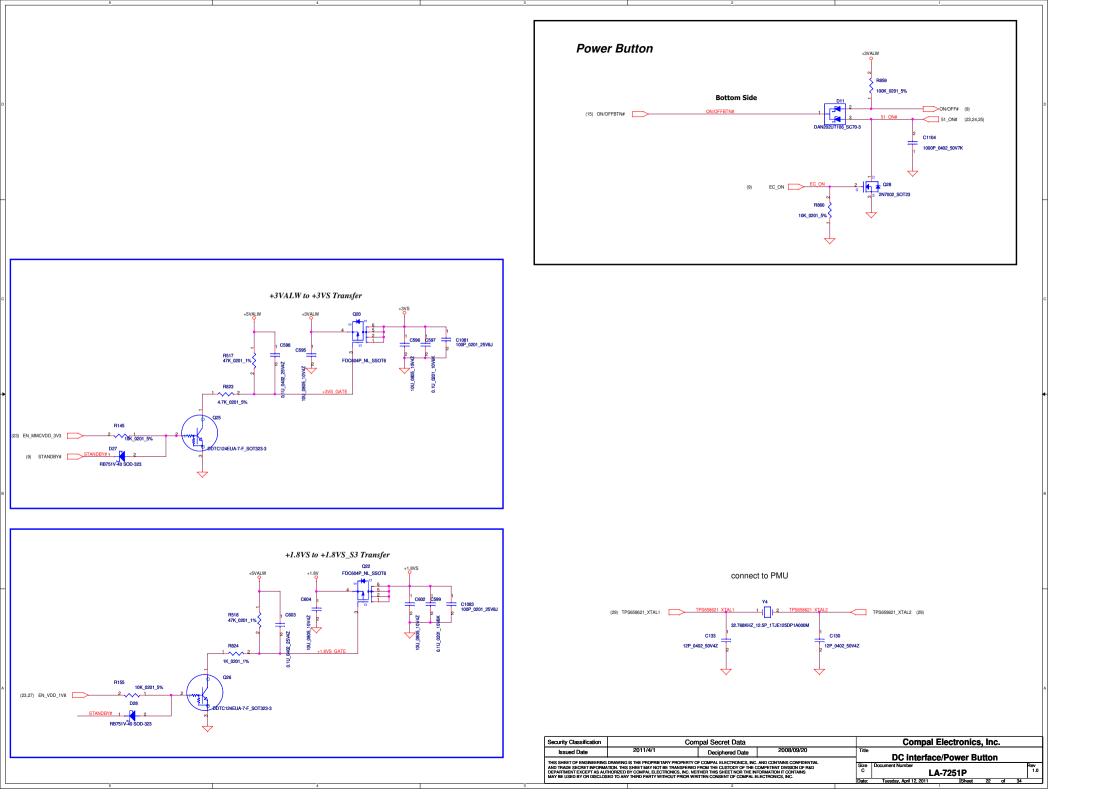


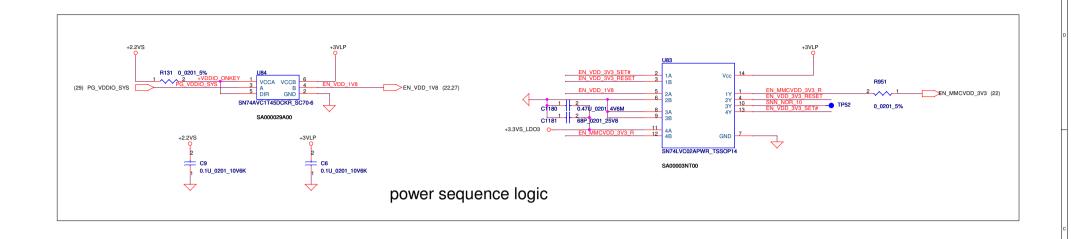


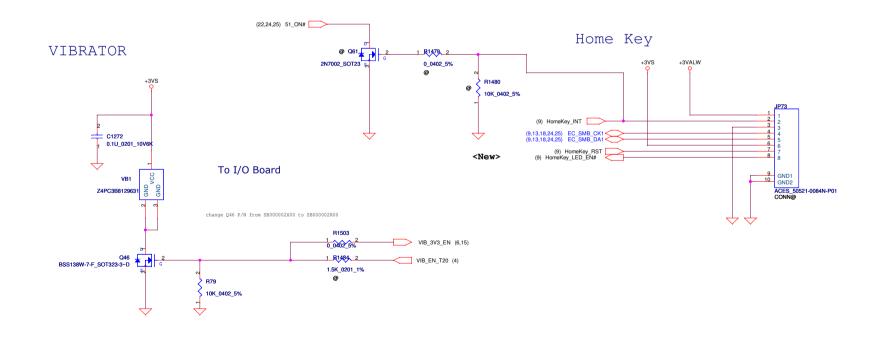




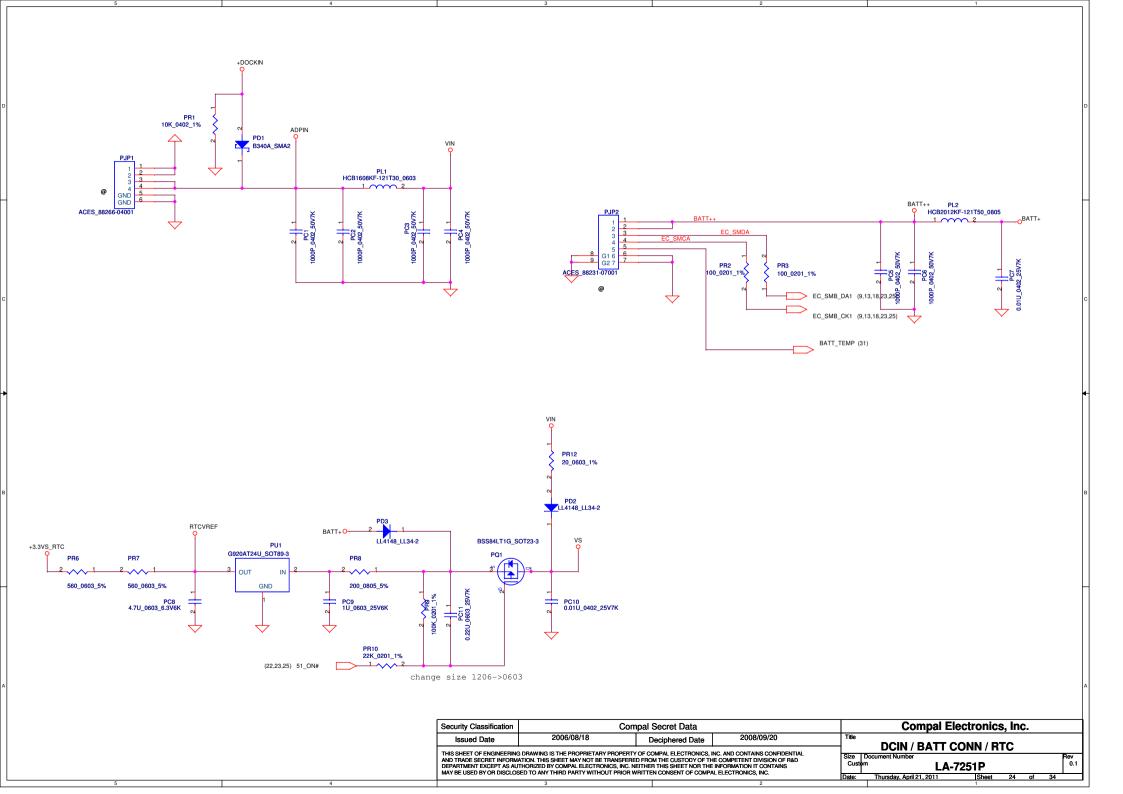


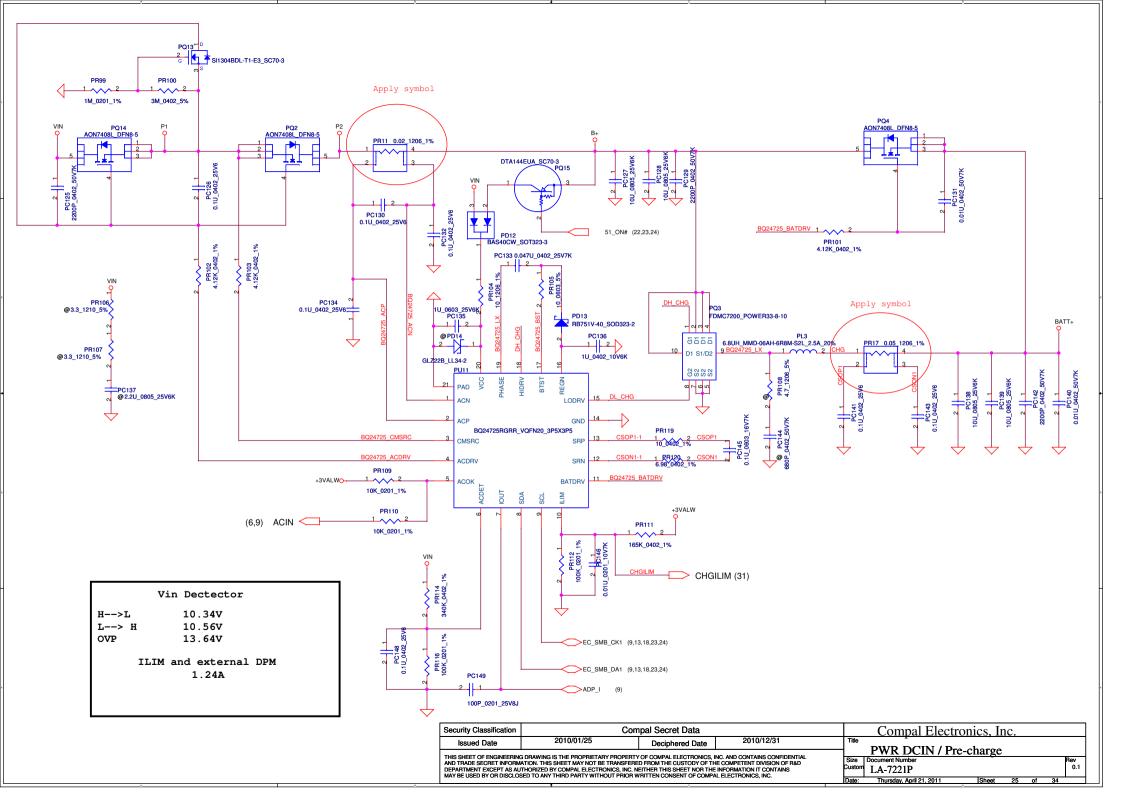


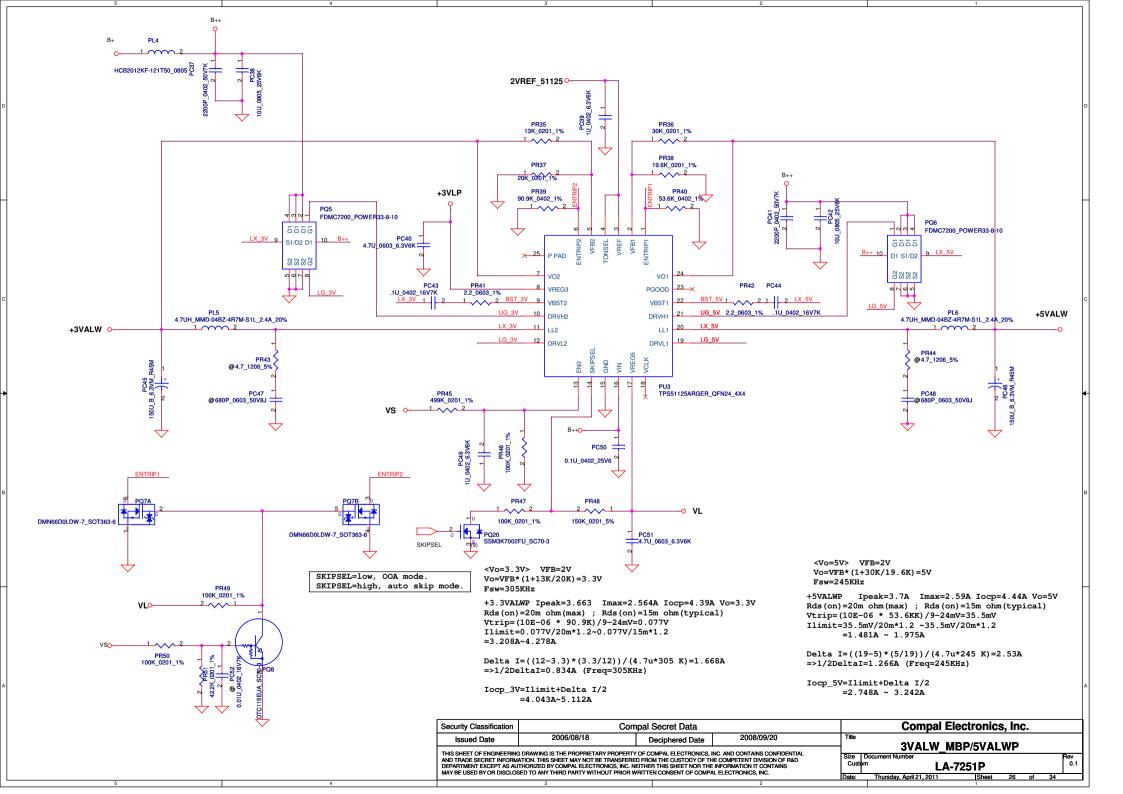


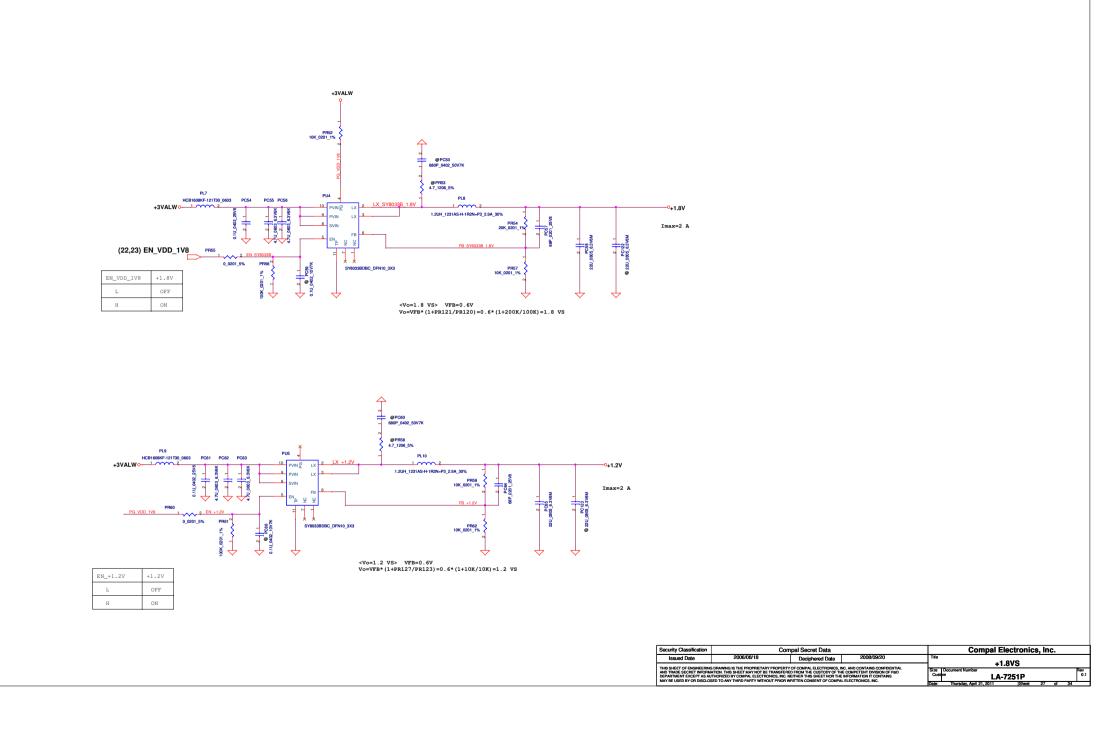


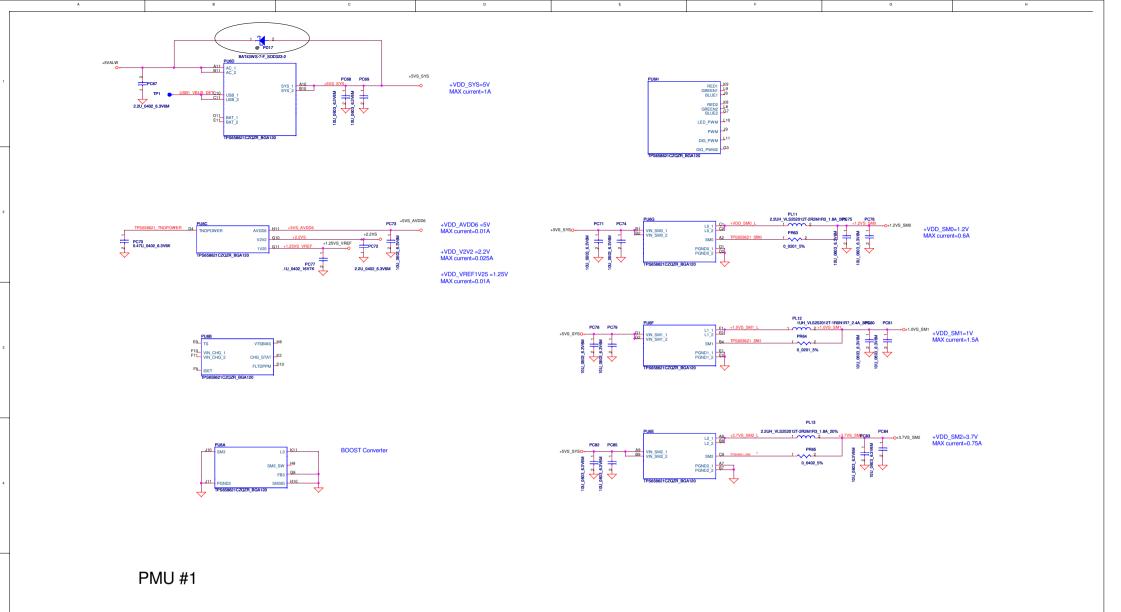
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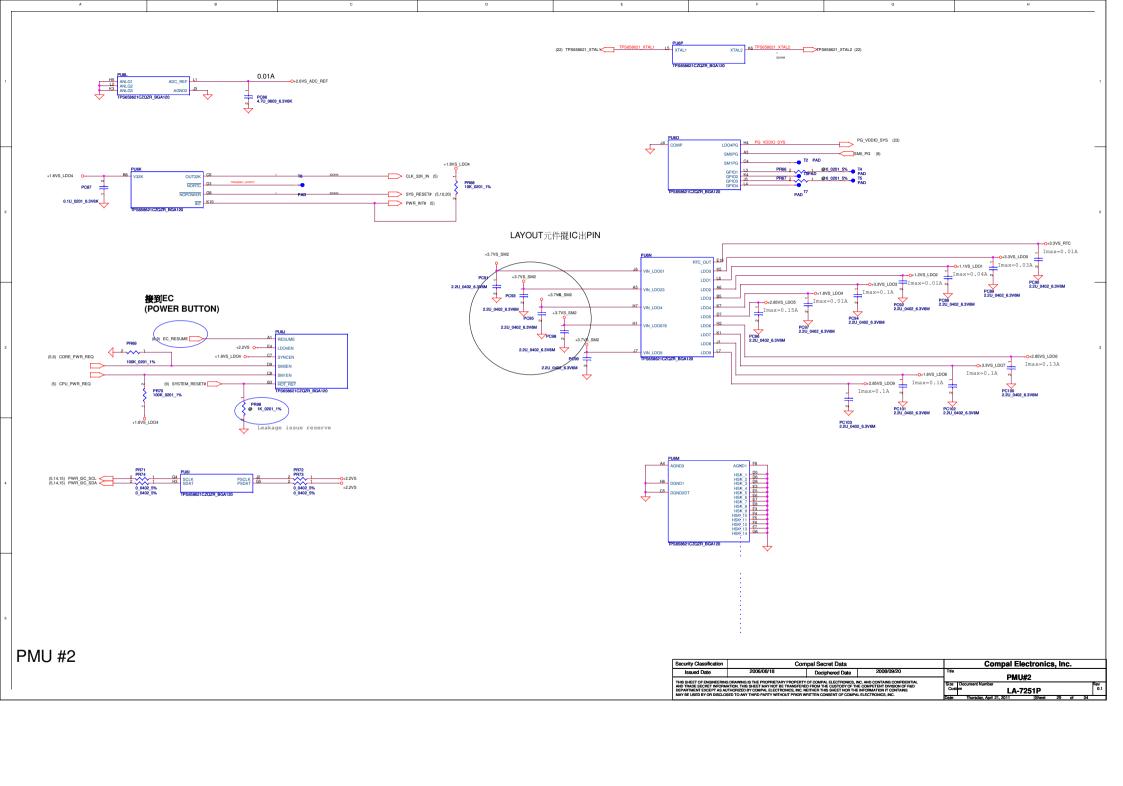


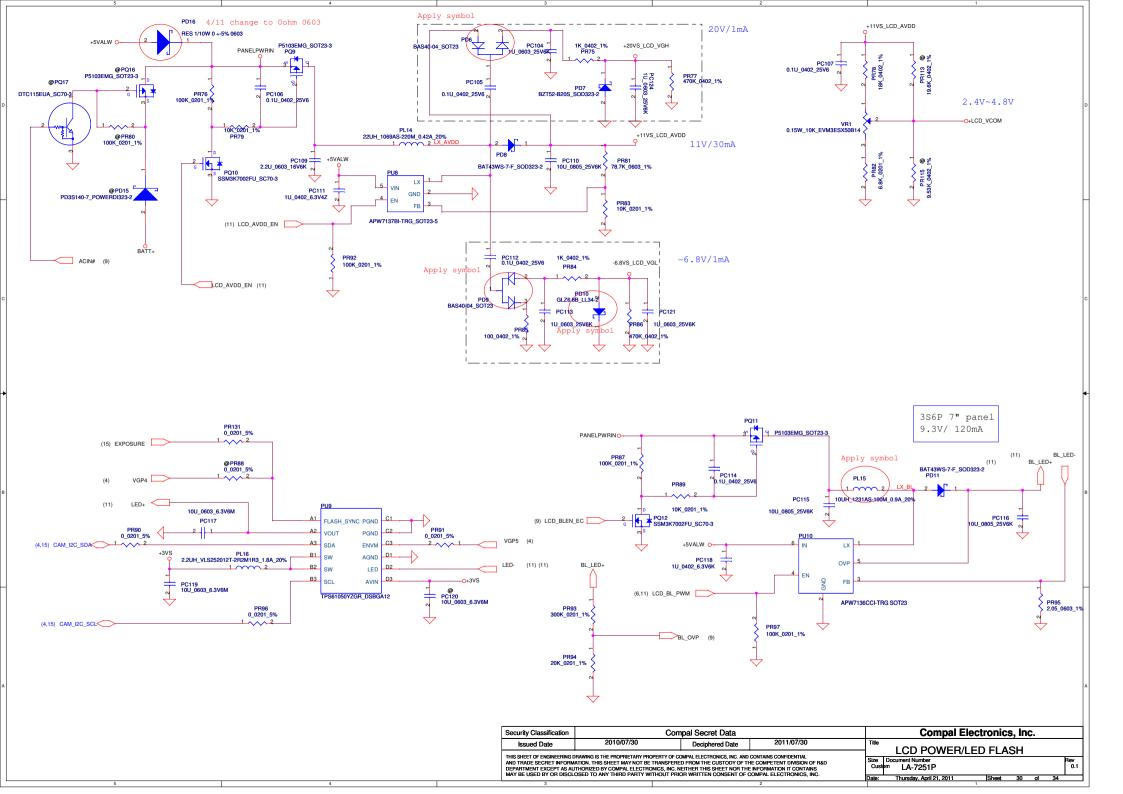




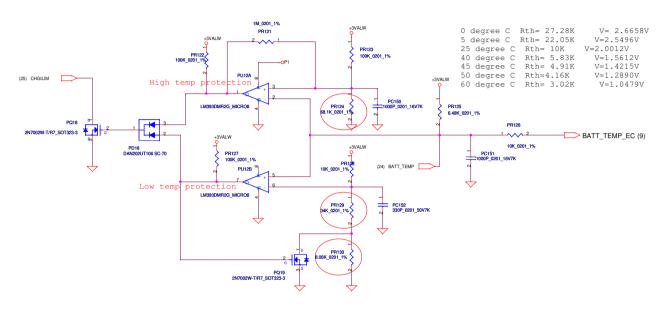


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O degree C protect, 5 degree C recovery. 50 degree C protect, 45 degree C recovery.



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Version change list (P.I.R. List)

1	Item	Fixed Issue	Reason for change	Rev.	PG#	Modify List	Date	Phase
2	1		Add 1000p to prevent noise coupling at battery TS pin.	0.1	25	Add 1000P_0201_16V at PC153.	2010/11/30	Before EVT
1	2		Change OTP setting, 45 degree C protect and	0.1	25		2010/11/30	Before EVT
	3	Prevent battery reverse and damage the	Follow FAE's suggestion, add resistors before SRN	0.1	25	Add 10_0402_1% at PR119.	2010/11/30	Before EVT
Setting change	4	Apply new PN for PD10.	Apply new PN for PD10.	0.1	30	Change PD10 from GLZ5.1B to GLZ6.8B.	2010/11/30	Before EVT
Company Comp	5	Modify +3VALWP OCP design	Modify +3VALWP OCP design	0.1	26	Change PR39 from 53.6K_0402_1% to 100K_0402_1%	2010/12/07	Before EVT
A	6	Design change	Modify BQ24725 schematic	0.1	25			Before EVT
Company to common 29		Change to common PN	Change to common PN	0.1		Change PC9,PC104,PC113,PC121,PC124 from SE000009R80 to SE000006900		Before EVT
Part Command part 1921 to 800 citation (2020001120) distance (1920001120) distance	8	Change to common PN	Change to common PN	0.1			2010/12/07	Before EVT
Procession part Procession	 9	Change to common PN	Change to common PN	0.1		SE00000QKN0 to SE00000QK00	2010/12/07	Before EVT
Part Communication Commu	0	For common part	PD1 3A SMA diode SCS00001I80 shortage issue	0.1	24		2010/12/07	Before EVT
2 Terminant part		For common part	Change BL choke to common PN	0.2	30			EVT
Proceedings Charge Charg		For common part	Change cap PN to common PN	0.2	25	Change PC136 from SE000000U00(1u_0402_16V)		EVT
For commany part Clausey display to commany PS 0.2 30 Change PS, PSP display from 35000057100 to 25000050710 2015/17/39 EVY	 3	Raise VGH voltage from 18V to 20V.	Raise VGH voltage from 18V to 20V.	0.2	30		2010/12/30	EVT
Changer CP Concess Date of Ambage whom ME_OVP Modify voltage divides resistors 0.2 30 Change PRM food 30% to 20%. 200/12/30 EVY	4	For common part	Change diode PN to common PN	0.2	30		2010/12/30	EVT
Thereams panel power imput doide	 5	For common part	Change CSR PN to common PN	0.2	25		2010/12/30	EVT
Charger CP close to IC max value. Charger CP setting near IC max value, vendor suggest change (npur CR value lower. Modify that for high and low tamp sense. 0.2 23 Change PBII from Nom to 20m ohm. 2019/12/30 EVT Sales PBI2, PBI3, P	 6	Prevent EC pin damage when BL_OVP	Modify voltage dividor resistor	0.2	30	Change PR94 from 30K to 20K.	2010/12/30	EVT
### Charger CP circuit Charger CP circuit Charger CP circuit Modify it for high and low temp same. 0.2 23 Changer FRIT FRITS, FRIT	 7	Increase panel power input doide	Increase panel power input doide	0.2	30	Change PD15 and PD16 to PD3S140.	2010/12/30	EVT
Modity charger CTP circuit		Charger CP close to IC max value.	Charger CP setting near IC max value, vendor suggest change inpur CSR value lower.	0.2		Change PR11 from 50m ohm to 20m ohm.	2010/12/30	EVT
The property of the main anutown issue	 9	Modify charger OTP circuit		0.2	25	PQ18, PQ19, PR121, PR122, PR123, PR124, PR125, PR126, PR127, PR128,	2010/12/30	EVT
to common part \$8000007880 (10000 16V K XFR 0201) For ESD part Change to include ESD dioed 0.2 30 P010 s 7012 change from \$8000007880 (S TR 2NT000W T/R7 1N 2011/01/10 EVT	0	Improve TI thermal shutdown issue	From vendor's suggestion, change PC77 from 1u to 0.1u	0.2	28	†	2010/12/30	EVT
Por ESD part Change to include ESD dioed 0.2 30 Poll & Poll & Change from \$8000006800 (S TR 2NT002N T/R7 IN SOT=23) to \$800007410 (S TR 2NSKNT002P UN SCT=23) to \$8000007410 (S TR 2NSKNT002P UN SCT=23) to \$80000007410 (S TR 2NSKNT002P UN SCT=23) to \$80000007410 (S TR 2NSKNT002P UN SCT=23) to \$80000007410 (S TR 2NSKNT002P UN SCT=23) to \$800000007410 (S TR 2NSKNT002P UN SCT=23) to \$800000000000000 (S TR 2NSKNT002P UN SCT=23) to \$8000000000000000 (S TR 2NSKNT002P UN SCT=23) to \$80000000000000000 (S TR 2NSKNT002P UN SCT=23) to \$8000000000000000000 (S TR 2NSKNT002P UN SCT=23) to \$800000000000000000 (S TR 2NSKNT002P UN SCT=23) to \$8000000000000000000 (S TR 2NSKNT002P UN SCT=23) to \$8000000000000000000000000000000000000	1	For common part	Change cap PN to common PN	0.2	31	PC150 & PC151 change from SE00000TG00 (1000P_0201_50V7K) to common part SE000007U80 (1000P 16V K X7R 0201)	2011/01/10	EVT
Modify panel power sequence	 2	For ESD part	Change to include ESD dioed	0.2	30	PQ10 & PQ12 change from SB000006800 (S TR 2N7002W T/R7 1N	2011/01/10	EVT
4 Modify panel power sequence Modify panel power sequence 0.2a 30 PR75 change from SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034300280(5 RES 1/16W 30K +-1% 0402) 2011/01/27 DVT to SD034300180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RES 1/16W 2K 1K +-1% 0402) 2011/01/27 DVT to SD034100180(8 RE	 3	For LED flash issue	modify LED flash schematic	0.2a	30	Add net EXPOSURE & add PRI31(0_0201_5%)	2011/01/11	EVT
Modify panel power sequence Modify panel power sequence 0.2a 30 PR84 change from SDD34300180(S RES 1/16W 1K +-1% 0402) to SDD34100180(S RES 1/16W 1K +-1% 0402)		Modify panel power sequence	Modify panel power sequence	0.2a	30	PR75 change from SD034100180(S RES 1/16W 1K +-1% 0402)	2011/01/27	DVT
Reduce negative current during CC mode to CP mode. 7 For common part Vendor not support SC2N2020U0T4(S DIO DAN202U) Add limit current resistor Add limit current during CC mode to CP mode. Add limit current during CC hange CP145 from SE000006580(S CER CAP 2.2U 16V K X5R 0603) Add PRI U 16V K X7R 0603) Add PRI U 16V K	 5	Modify panel power sequence	Modify panel power sequence	0.2a	30	PR84 change from SD034300180(S RES 1/16W 3K +-1% 0402)	2011/01/27	DVT
7 For common part Vendor not support SC2N202U0T4(S DIO DAN202U) 0.3 31 Change PD18 from SC2N202U0T4(S DIO DAN202U) to SC2N202U010 2011/02/10 PVT (S DIO DAN202UT106 SC-70) Add limit current resistor Add limit current resistor 0.3 24 Add PR12 (S RES 1/10W 20 +-1% 0603) 2011/02/17 PVT	 5	Reduce negative current during CC mode to CP mode.	Reduce negative current during CC mode to CP mode.	0.2a	25	Change PC145 from SE000006S80(S CER CAP 2.2U 16V K X5R 0603)	2011/01/27	DVT
Add limit current resistor Add limit current resistor 0.3 24 Add PR12 (S RES 1/10W 20 +-1% 0603) 2011/02/17 PVT	 7		Vendor not support SC2N202U0T4(S DIO DAN202U)	0.3	31	Change PD18 from SC2N202U0T4(S DIO DAN202U) to SC2N202U010	2011/02/10	PVT
9	 B	Add limit current resistor	Add limit current resistor	0.3	24	+	2011/02/17	PVT
+							 	ļ·
1								
	10	1	<u> </u>		† -	†		

<2010/11/17> By Harry FVT <2010/11/01> P12- add C54/C55/R245/R246 <2010/10/05> P04 - NET: HDMI HPD R change to HDMI HPD SRC P12 - add R182(Head DET#) pull-high on MB P15 - CAM2 OE pull down(High active for 2M camera) P04 - DFI R211 P19 - ADD U151, U152, R1411, C1464 P05 - DEL R179 P06 - R109 Change to 0-ohm <2010/11/18> By Harry ADD NET: USB1_ID <2010/11/03> update Power schematic DEL NET: DAP MCLK1 FM2018 P04 - ADD NET: DOCK ON P09 - ADD NET: HDMI HPD, HDMI HPD2, DOCK ON <2010/11/22> By Harry ADD R1348, R1349, R1350, R1351 P11 - Modify U97 package to S023-5 P09 - ADD R1352 For IR INT Page9 add EC ESB BUS Modify JP58(Touch Panel) Library ADD NET: USB1 ID, IR INT P12 - Modify JP55 Library P11 - Change U150 package P13 - Modify internal MIC Library <2011/02/11> P12 - C1414, C1415, C1416, C1419 Change to 5600p P16 - Modify SW6 Library DEL R1223, R1221, R1220 P14 - ADD R1522 P18 - DEL R1377, R1378, R1409 P13 - DEL R1250 Update power circuit Modify U109 package to S023-5 ADD R1389, R1390, R1391, R1392 P19 - Modify U97 package to S023-5 P14 - ADD R1394, R1395 <2011/02/18> P15 - DEL R136, R139, R140, R143, R144 P17 - DEL R1307, R1344 P09 - ADD R1528 <2010/11/05> P19 - Modify USB circuit P12 - ADD Q64~Q66, R1523~R1527 P23 - DEL R148 P16 - Modify JP12(Docking) Library DEL R1495, R1498 P19 - Modify JP70(Micro USB) Library P16 - ADD C1484 Update power circuit Update power circuit <2010/10/08> P04 - R36, R39 Change package size to 0201(2.2K SD00000TH00) <2010/11/08> <2011/03/03> R117, R1022, R112 Change package size to 0201(100K) R11 Change package size to 0201(10K) P04 - DEL R931, C1217 P09 - change R1417 to 33K-ohm(Board ID) P12 - Q64~Q66 change to SB00000BS00 P09 - ADD R1412~R1419 and Q59, Q60 P05 - R45, R46, R226, R48 Change package size to 0201 P10 - ADD R1420 R1496 change to 25.5K-ohm P06 - R54, R57, R110, R111, R114, R1348, R1349, R1350, R1351 Change package size to 0201 P11 - ADD D31 for LED Flash R1500 change to 46.4K-ohm P08 - R460, 461 Change package size to 0402 P09 - R1161, R1174 Change package size to 0402 P12 - ADD R1421~R1425 and C1465, C1466 P16 - mount: U149, C1452~C1457, R1396, R1398, R1404 for 3G SKU R1352 Change package size to 0201 P13 - ADD JMIC1, JMIC2, R1426~R1430 for DMIC P18 - nu-mount: R1363, R1382, R1357, R1362 P15 - DEL 5M Camera circuit mount: R1372, R1354, R1367 NET: IR_INT Change to IRDA_INT P11 - R1405 Change package size to 0201 P17 - ADD RF switch circuit change R1496 to 422-ohm P18 - ADD R1439 change R1373, R1358 to 47K-ohm R1208, R1209 Change package size to 0402 P12 - R1224, R1225, R1147, R1145, R1144, R1148, R1059 Change package size to 0402 P22 - DEL Power Button circuuit P23 - change JP73.1 NET to +3VALW R1299, R181 Change package size to 0201 P23 - DEL P-Sensor circuuit nu-mount: O61, R1479, R1480 P13 - C1375, C1372, C1376, C1373, C1133, C1135 Change package size to 0402 P14 - R1301, R1 Change package size to 0402 <2010/11/09> <2011/03/08> R1394, R1395, R1296 Change package size to 0201 P03 - modify I2C address table P15 - R1292, R23, R37, R44, R47, R52 Change package size to 0201 P15 - Update JP2 Pin arrangement P16 - R28 Change package size to 0402 P05 - R1444 change to 3G@ P17 - Remove RF switch circuit to IO board R1401 Change package size to 0201 P22 - Add Power Button circuit P09 - modify board ID table P17 - R1157, R1158 Change package size to 0402 P12 - Change R245, R246 to 9.1-ohm for 3G@ P18 - R1368, R1374, R1388, R1370, R1365, R1385, R1356, R1375 Change package size to 0201 P14 - nu-mount U132 <2010/11/15> P19 - R1393, R1406, R1172 Change package size to 0201 P15 - nu-mount: R1513 P04 - DEL NET: DOCK_ON D30 NET Change to +USB VOUT mount: R1514 Change NET: PROX INT# to P INT# - C598, C603, R67 Change package size to 0402 P16 - Change R1470, R1472 to 600-ohm at 100MHz for 3G@ P05 - ADD NET: DOCK ON, IR INT, Home POUT, Home LED ON R859, R860 Change package size to 0201 P19 - nu-mount: C1433, C1450 ADD R1444~R1446, R1449, D32 P06 - Change R109 to 10K-ohm <2011/04/28> Change NET: USB1 ID to +AVDD USB <2010/10/12> P05 - Change R1444 to SD028100280 P09 - DEL R1177~R1179 P16 - Add R1407 for DOCK DET R# DEL NET: USB1 ID, DOCK DET L#, SLEEP MODE Add R1408, O58 for HEAD R DET# ADD NET: POUT, IR_INT, FM2018_EN, P_INT# P11 - Change NET: LED- to BL LED-, LED+ to BL LED+ <2010/10/15> Change JP58 Pin arrangement P04 - Add NET: LS_EN#, I2C_RST P12 - Swap D5, D6 P09 - Add NET: EC_OE_OFF P13 - Remove MIC circuit P18 - R1376, R1359, R1373, R1358, R1363, R1382 Change package size to 0201 P15 - Change NET: +5VALW to +3VALW R519, R520 mount P16 - DEL R1407, R72 Update JHDMI connector P17 - Swap L50 P19 - Del U151, C1463, C1464, R1406 P18 - Change L91~L94 to SM070001S00 P20 - Del R50, R53, R55, R60 Swap L93, L94 for layout P21 - Del R1202~R1209 P19 - Change JP70 library Updata Power Schematic ADD R1447, R1448 P23 - ADD JP72 for Home Kev <2010/10/21> P11 - C121(4.7uF) Change package size to 0603 P16 - DEL U133 P19 - C121(4.7uF) Change package size to 0603 ADD Q59 P23 - ADD U3, U5 Security Classification Compal Secret Data Compal Electronics, Inc. 2008/09/20 2011/4/1 Issued Date Deciphered Date

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Date: Thursday, April 28, 2011 | Sheet 33 of 34

